

Legacy Electronics Offers New DDR4 Registered DIMM Modules In VLP (Very Low Profile) Form Factor

Legacy's Embedded Industrial OEM Customers Are Now Able to Have Access to the Lower Power, High Bandwidth and Density Benefits of the Newest DRAM Technology

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CANTON, S.D.--(BUSINESS WIRE)--[Legacy Electronics](#), a USA designer and manufacturer of high-density memory modules, circuit boards and solid-state drives (SSDs), has announced new DRAM technology that will deliver notable power savings of 20% or more and significant increased performance over DDR3. The new DDR4 in VLP modules will benefit blade servers, networking and telecom applications where space is very tight.

"The Legacy family's ongoing strategy is to increase support for the embedded infrastructure, AdvancedTCA (ATCA) platforms and high-end enterprise server markets. These DDR4 modules are offered in densities ranging from 4 -16 gigabytes (GB)," said Mike Ridling, director of business development for Legacy. "In today's server environments managing a power budget and limiting heat dissipation are key considerations. DDR4 running at lower power, 1.2 volts, offers tangible advantages," added Ridling.

At data rates reaching 2,400 Mb/s combined with the significant power savings and high density compact design Legacy's DDR4 VLP product, available now, is ideal for high-end enterprise and storage systems as well as cloud server providers that support applications requiring large memory footprints, such as in-memory databases and real-time analytics.

About Legacy Electronics

Legacy Electronics offers a full line of flash-based SSD products, and specializes in mSATA (MO-300A), Half-Slim (MO-297) and standard 2.5" drives.

Headquartered in South Dakota, Legacy Electronics is a woman owned, U.S.-based, ISO 9001:2000-certified contract manufacturer, designer and tester of high-speed, high-density memory modules, printed circuit boards, and other computer products. Legacy Electronics holds several patents and trademarks, including those for its Canopy® chip-stacking process technology, and its Multiple Device Canopy® (MDC®) for embedded computing and high-density VLP (very low profile) modules. For more information: www.legacyelectronics.com